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## PMP3799\_REVE BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	1000pF	Capacitor, Ceramic, 2kV, C0G, 10%	1812	Std	Std
1	C102	47pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	C1608C0G1H470K	TDK
1	C11	100uF	Capacitor, Aluminum, 25V, ZL Series	0.200 * 0.435 inch	25V ZL 100uF	Rubycon
9	C12, C13, C14, C15, C16, C17, C23, C100, C101	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C19	220pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
2	C2, C3	2.2uF	Capacitor, Ceramic, 100-V, X7R, 20%	1210	C3225X7R2A225M	TDK
1	C20	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
1	C200	0.1uF	Capacitor, Ceramic, 250V, X7R, 15%	1206	Std	Std
1	C21	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C4	220uF	Capacitor, Aluminum Electrolytic, 35V	0.315 inch	35V ZL 220uF 10x16mm	Rubycon
1	C5	1uF	Capacitor, Ceramic, 50V, X7R, 15%	1206	Std	Std
1	C6	0.047uF	Capacitor, Ceramic, 250-V, X7R	1206	C3216X7R2E473M	TDK
5	C7, C8, C9, C10, C18	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
4	D1, D2, D3, D9	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
1	D200	ES1D	Diode, Super Fast Rectifier, 200V, 1A	0.220 x 0.115 inch	ES1D	Diodes
2	D6, D7	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
6	J1, J2, J3, J4, J5, J6	8600-0-05-xx-00-00-03-0	Header, Single pin	0.072 x 1	8600-0-05-01-00-00-03-0	Mill-Max
1	L300	33 uH	Coupled Inductor, Custom	0.828 x 0.882 inch	PA2645NL	Pulse
4	Q1, Q2, Q4, Q5	IRF7494	MOSFET, N-Chan, 150V, 44 miliohm, 5.2A	SO8	IRF7494	IR
1	Q3	IRF6216	MOSFET, P-ch, 150-V, 2.2-A, 240-milliOhms	SO8	IRF6216	International Rectifier
1	Q6	MMBT3904	Bipolar, NPN, 40-V, 200-mA	SOT23	MMBT3904LT1	On Semi
1	Q7	MMBT3906	Bipolar, PNP, 40-V, 200-mA	SOT23	MMBT3906LT1	On Semi
5	R1, R2, R3, R14, R24	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R10, R18, R23	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	301	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R101	1.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R104	20	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	1.62k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	7.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R15, R16	75k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R19, R300	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R20, R27	DNP	Do Not Populate	0603	N/A	N/A
1	R200	49.9k	Resistor, Chip, 1/4W, 5%	1210	STD	STD
1	R202	750k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R21, R22	2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R25, R28	20k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R29	1.43k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	0.04	Resistor, Chip, 1W, 5%	2512	STD	STD
2	R7, R9	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	4.02k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	PA2583NL	Transformer, Custom, Forward	0.827 x 0.882 inch	PA2583NL	Pulse
2	TP1, TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP3, TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
1	U1	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	Texas Instruments
1	U100	LM317MQDCYR	IC, 3 Terminal Adjustable Regulator	SOT223	LM317MQDCYR	TI

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2	U101, U103	TPS71550DCK	IC, High Input Voltage, Micropower LDO, 5V	SOP-5 (DCK)	TPS71550DCKR	TI
1	U2	ISO721MD	IC, High Speed Digital Isolator	SO-8	ISO721MD	TI
1	U3	TPS28225D	IC, High Frequency 4-Amp MOSFET Driver	SO8	TPS28225D	TI
1	U4	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
1	U5	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

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